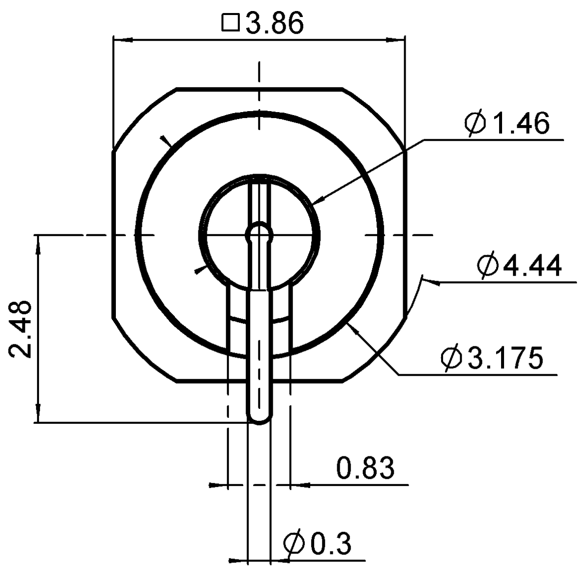
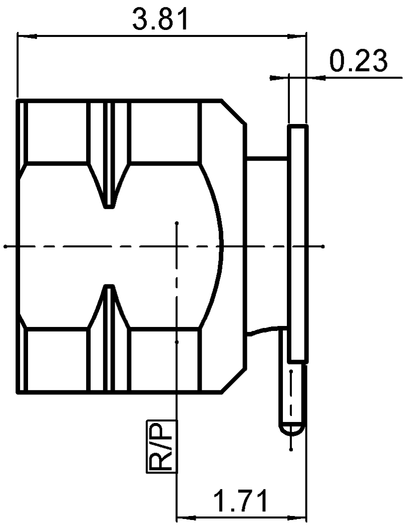
SMT PLUG RECEPTACLE

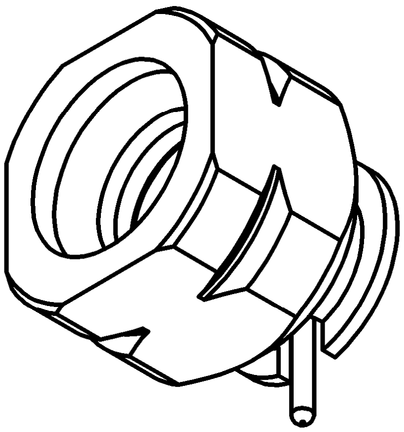
FULL DETENT

R201.508.000

Series : **SMPM**







All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	**BERYLLIUM COPPER**	**GOLD 0.5 OVER NICKEL 2**
CENTER CONTACT	**BERYLLIUM COPPER**	**GOLD 0.5 OVER NICKEL 2**
OUTER CONTACT	-	-
INSULATOR	**PEEK**	
GASKET	-	
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 1042 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

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PACKAGING

Standard	Unit	Other
100	**‘W’ option**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance	**50**	Ω
Frequency	**0-20**	GHz
VSWR	****** + **0,0000**	x F(GHz) Maxi
Insertion loss	**0.12**	√F(GHz) dB Maxi
RF leakage	**- (** **NA**	- F(GHz)) dB Maxi
Voltage rating	**335**	Veff Maxi
Dielectric withstanding voltage	**500**	Veff mini
Insulation resistance	**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**6.7*****	N mini
Axial force – Opposite end	**6.7*****	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**0,2700**	g

SPECIFICATION

ENVIRONMENTAL

Operating temperature	**-65/+165**	° C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

OTHER CHARACTERISTICS

Assembly instruction

Others :
** 1.15 to 12GHz
** 1.35 to 20GHz
***after soldering on PCB

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SOLDER PROCEDURE

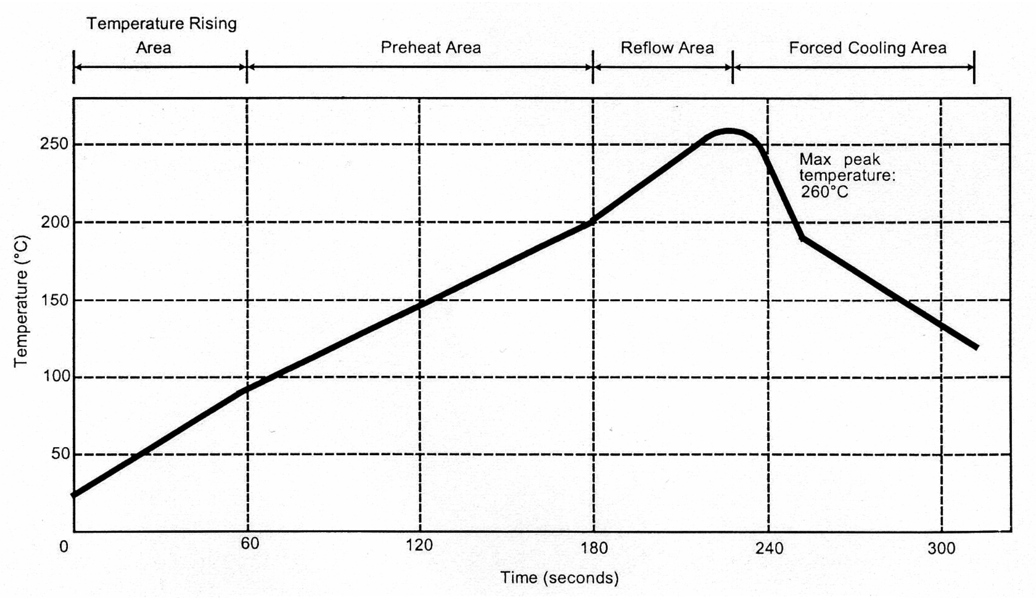
1. Deposition of solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
   We advise a thickness of 150 µm. Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

3. Soldering by infra-red reflow.
   Below, please find the typical profile to use.

4. Cleaning of printed circuit boards.

5. Checking of solder joints and position of the component by visual inspection.



Parameter	**Value**	**Unit**
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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RECOMMENDED PAD DIMENSIONS

Substrat: RT5880 thickness 0.254 mm, with copper layer 35µm on both sides.
Add vias between both sides along upper ground plane according to engineering practise.